



Material Content Data Sheet



Sales Product Name		IPB072N15N3 G		Issued		20. July 2018		
MA#		MA000771496						
Package		PG-TO263-3-2		Weight*		1567.51 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	17.562	1.12	1.12	11204	11204
leadframe	non noble metal	iron	7439-89-6	0.304	0.02		194	
	inorganic material	phosphorus	7723-14-0	0.091	0.01		58	
	non noble metal	copper	7440-50-8	304.026	19.40	19.43	193955	194207
wire	non noble metal	aluminium	7429-90-5	9.078	0.58	0.58	5791	5791
encapsulation	organic material	carbon black	1333-86-4	10.020	0.64		6392	
	plastics	epoxy resin	-	110.217	7.03		70313	
	inorganic material	silicondioxide	60676-86-0	547.743	34.94	42.61	349435	426140
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6161	6161
plating	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	146	147
	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
solder	noble metal	silver	7440-22-4	0.255	0.02		163	
	non noble metal	tin	7440-31-5	0.204	0.01		130	
	non noble metal	lead	7439-92-1	9.743	0.62	0.65	6215	6508
heatspreader	non noble metal	iron	7439-89-6	0.548	0.04		350	
	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	copper	7440-50-8	547.666	34.93	34.98	349387	349842
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com